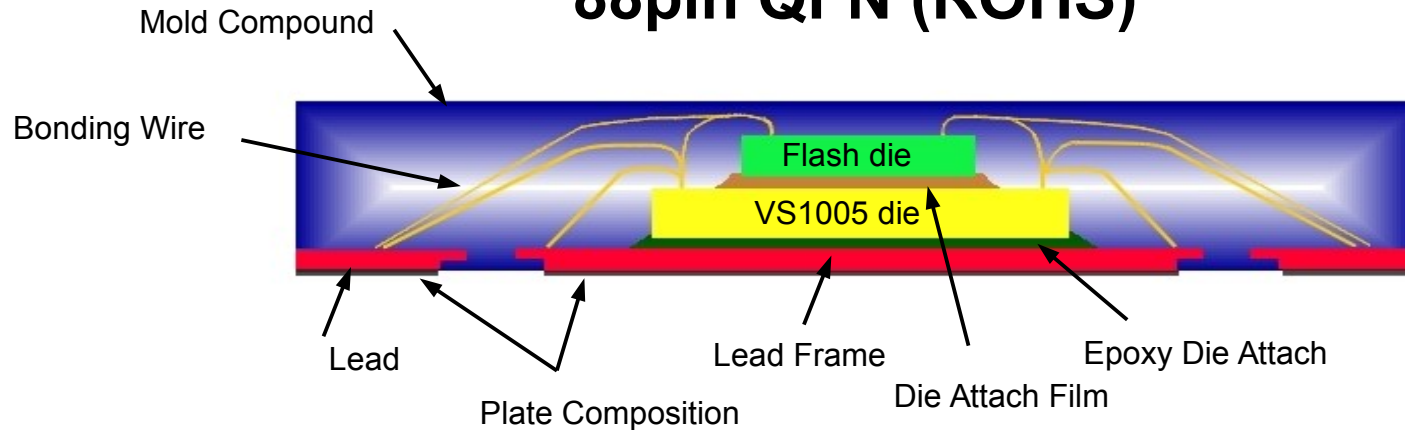


Doc: C
Rev: 1

Cross-Section View VS1205GF/VS1005GF 88pin QFN (ROHS)



SUBSTRATE (Lead Frame)

Plate composition

100% Sn

Plate thickness

200~1000 micro inches

Material

Lead Frame

C194 (FH)

Epoxy Die Attach

Bottom (VS1205 or VS1005 die) AP4200

Die Attach Film

Top (Flash memory die) IDU0C1-20E

Bonding Wire

GOLD Alloy (0.8 MIL)

Mold Compound

EME G770HC